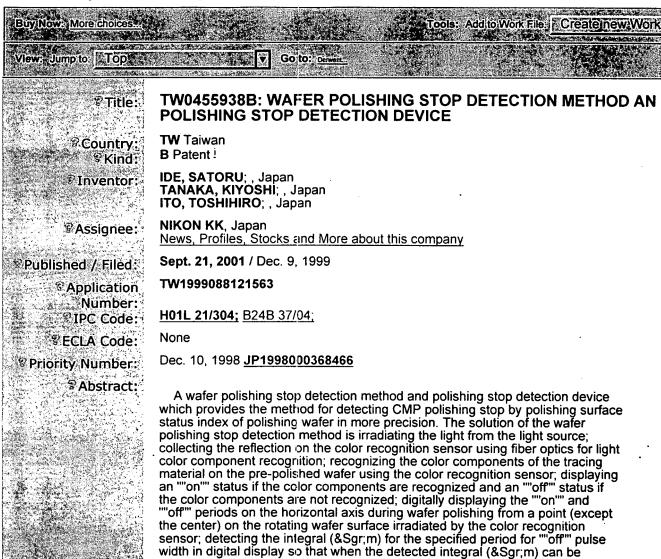


The Delphion Integrated View: INPADOC Record



consistent with the integral value (&Sgr;n) for the specified period for ""off" pulse

width of predetermined best wafer polishing stop, defining it as the wafer

polishing stop.

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Buy PDF	Publication	Pub. Date	Filed	Title			
	US6342166B1	Jan. 29, 2002					
æ	<u>US6342166</u>	Jan. 29, 2002	Dec. 6, 1999	Method of detecting end point of p wafer and apparatus for detecting polishing			
	TW0455938B	Sept. 21, 2001	Dec. 9, 1999	WAFER POLISHING STOP DETE METHOD AND POLISHING STOP DEVICE			
		, ,	Dec. 9, 1999	METHOD FOR DETECTING POLI POINT OF WAFER AND APPARA DETECTING THE POLISHING EN			
	JP2000183002A2	June 30, 2000	Dec. 10, 1998	METHOD AND DEVICE FOR DET WAFER POLISH END-POINT			
5 f	5 family members shown above						

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